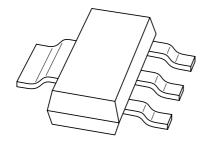
DISCRETE SEMICONDUCTORS

DATA SHEET



PBSS4350Z50 V low V_{CEsat} NPN transistor

Product specification Supersedes data of 2003 Jan 20 2003 May 13





50 V low V_{CEsat} NPN transistor

PBSS4350Z

FEATURES

- · Low collector-emitter saturation voltage
- High collector current capability: I_C and I_{CM}
- High collector current gain (hFE) at high IC
- Higher efficiency leading to less heat generation
- Reduced PCB area requirements compared to DPAK.

APPLICATIONS

- · Power management
 - DC/DC converters
 - Supply line switching
 - Battery charger
 - Linear voltage regulation (LDO).
- Peripheral drivers
 - Driver in low supply voltage applications, e.g. lamps, LFDs
 - Inductive load driver, e.g. relays, buzzers, motors.

DESCRIPTION

NPN low V_{CEsat} transistor in a SOT223 plastic package. PNP complement: PBSS5350Z.

MARKING

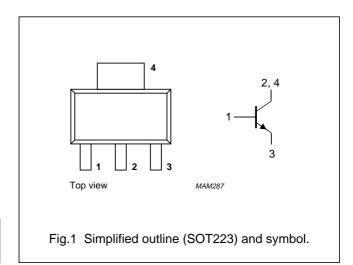
TYPE NUMBER	MARKING CODE
PBSS4350Z	PB4350

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{CEO}	collector-emitter voltage	50	V
I _{CM}	peak collector current	5	Α
R _{CEsat}	equivalent on-resistance	<145	mΩ

PINNING

PIN	DESCRIPTION	
1	base	
2	collector	
3	emitter	
4	collector	



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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	60	V
V _{CEO}	collector-emitter voltage	open base	_	50	V
V _{EBO}	emitter-base voltage	open collector	_	6	٧
I _C	collector current (DC)		_	3	Α
I _{CM}	peak collector current		_	5	А
I _{BM}	peak base current		_	1	Α
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; notes 1 and 3	_	1.35	W
		T _{amb} ≤ 25 °C; notes 2 and 3	_	2	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm².
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 6 cm².
- 3. For other mounting conditions see "Thermal considerations for SOT223 in the General Part of associated Handbook".

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	in free air; notes 1 and 3	92	K/W
		in free air; notes 2 and 3	62.5	K/W

Notes

- 1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm².
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 6 cm².
- 3. For other mounting conditions see "Thermal considerations for SOT223 in the General Part of associated Handbook".

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

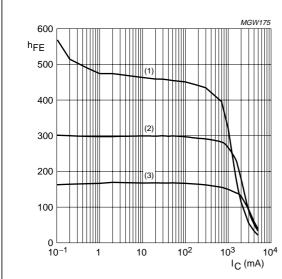
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	V _{CB} = 50 V; I _E = 0	_	_	100	nA
		V _{CB} = 50 V; I _E = 0; T _j = 150 °C	_	_	50	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0$	_	_	100	nA
h _{FE}	DC current gain	V _{CE} = 2 V; I _C = 500 mA	200	_	_	
		V _{CE} = 2 V; I _C = 1 A; note 1	200	_	_	
		V _{CE} = 2 V; I _C = 2 A; note 1	100	_	_	
V _{CEsat}	collector-emitter saturation	$I_C = 500 \text{ mA}; I_B = 50 \text{ mA}$	_	_	90	mV
	voltage	I _C = 1 A; I _B = 50 mA	_	_	170	mV
		$I_C = 2 \text{ A}$; $I_B = 200 \text{ mA}$; note 1	_	_	290	mV
R _{CEsat}	equivalent on-resistance	I _C = 2 A; I _B = 200 mA; note 1	_	110	<145	mΩ
V_{BEsat}	base-emitter saturation voltage	I _C = 2 A; I _B = 200 mA; note 1	_	_	1.2	V
V_{BEon}	base-emitter turn-on voltage	V _{CE} = 2 V; I _C = 1 A; note 1	_	_	1.1	V
f _T	transition frequency	I _C = 100 mA; V _{CE} = 5 V; f = 100 MHz	100	_	_	MHz
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	_	_	30	pF

Note

^{1.} Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

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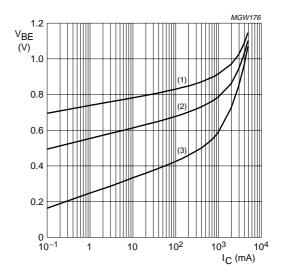
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 $V_{CE} = 2 V$.

- (1) T_{amb} = 150 °C.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

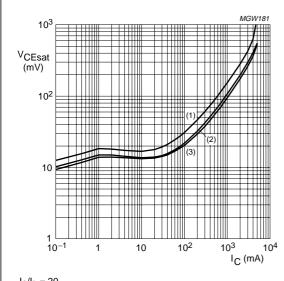
Fig.2 DC current gain as a function of collector current; typical values.



 $V_{CE} = 2 V$.

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) $T_{amb} = 25 C$.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

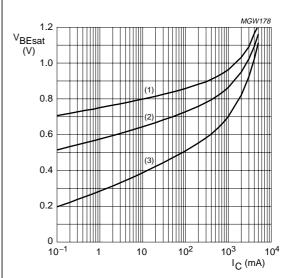
Fig.3 Base-emitter voltage as a function of collector-current; typical values.



 $I_{\rm C}/I_{\rm B}=20.$

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.4 Collector-emitter saturation as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 20$.

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- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.5 Base-emitter saturation voltage as a function of collector current; typical values.

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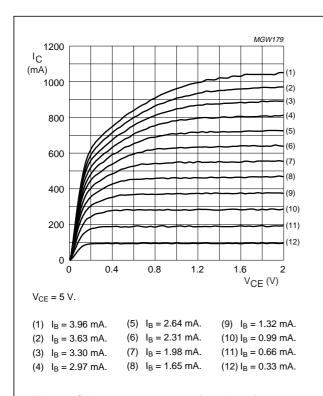
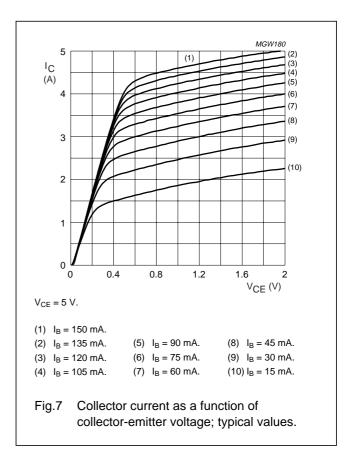
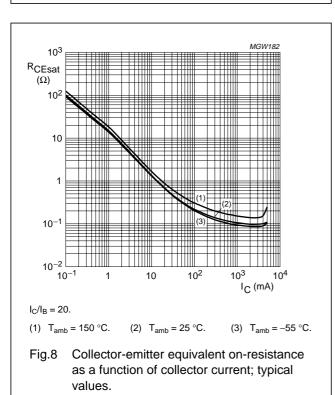


Fig.6 Collector current as a function of collector-emitter voltage; typical values.





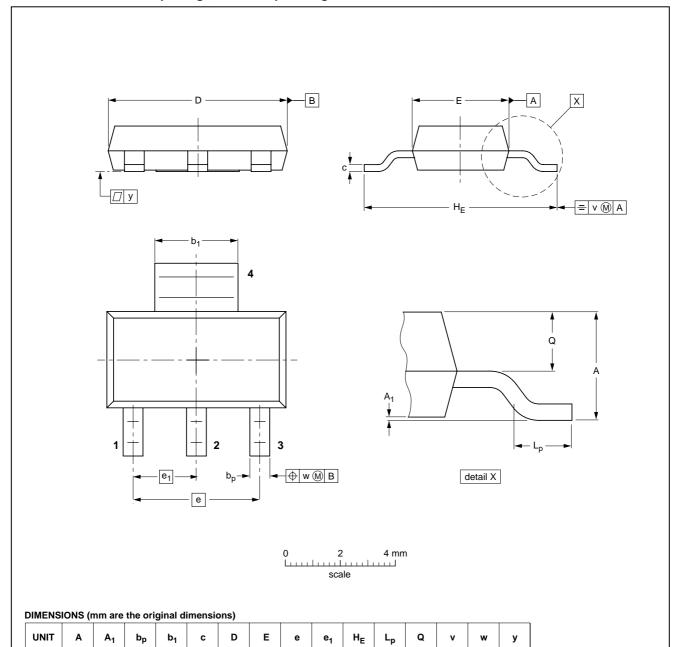
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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



OUTLINE	REFERENCES EUROPEAN ISSE			ICCUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT223			SC-73		-97-02-28 99-09-13

0.95

0.85

0.2

0.1

0.1

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0.80

0.60

1.8

1.5

mm

0.10

0.01

3.1 2.9 0.32 0.22 6.7 6.3 3.7 3.3

4.6

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Printed in The Netherlands

613514/03/pp12

Date of release: 2003 May 13

Document order number: 9397 750 11057

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